

REMARKS

Claims 2-8 are pending in this application, of which claim 8 has been amended. No new claims have been added.

Claims 2-3 and 8 stand rejected under 35 USC §102(b) as anticipated by U.S. Patent 5,825,192 to Hagihara (hereinafter "**Hagihara**").

Applicant respectfully traverses this rejection.

Hagihara discloses a probe card device used in a probing apparatus for testing the electrical characteristics of a semiconductor wafer by bringing bump electrodes into contact with a plurality of electrode pads of the wafer. The probe card device includes a probe card, a support block for supporting the probe card, and a pushing mechanism for pushing the probe card toward the wafer. The pushing mechanism includes a pushing member divided into a plurality of blocks, and a support member for supporting each of the divided blocks. These plural blocks are movable independently and serve to push the wafer in a manner to follow a surface profile of the wafer.

The Examiner has urged that "bolts" 52 and 53 serve as a parallelism adjusting means.

Applicant respectfully disagrees.

Hagihara's device is at least able to adjust a degree of parallelism of the membrane 33 placed under the support block 31 in such a way that the pushing member (support member 50 and blocks 39a supported by the same) swingably pushes the membrane 33. More particularly, a ball 54 fixed to the lower end of the bolt 53, which screws through the central portion of the

support block 31, abuts against a recess 52a formed in a head portion of the bolt 52 and thereby the pushing member swingably pushes membrane 33 for parallelism adjustment. (Please see col. 6, lines 29-47)

This is in contrast to the means for adjusting a degree of parallelism in the instant application. In particular, in the instant application, a coil spring 420 is interposed between two flange sections, namely, a flange section 321 provided outside of the contactor unit 300 and a flange section 411 provided with the support member at a greater distance than the contactor unit from the substrate body 100. A surface of the contactor unit is pushed respectively by a plurality of parallelism adjusting means in order to adjust spacing between the contactor unit and the substrate body. Accordingly, claim 8 has been amended to recite this distinction.

Thus, the 35 USC §102(b) rejection should be withdrawn.

The Examiner has indicated that claims 4-7 would be allowable if rewritten in independent form. Applicant respectfully defers this action until a FINAL Office Action, if any, is received.

In view of the aforementioned amendments and accompanying remarks, claims 2-8, as amended, are in condition for allowance, which action, at an early date, is requested.

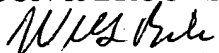
If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

U.S. Patent Application Serial No. 10/622,464
Response to Office Action dated November 29, 2004

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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PATENT TRADEMARK OFFICE

Enclosures: Petition for Extension of Time

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